L Number	Hits	Search Text	DB	Time stamp
1	8739	257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783	USPAT, US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 15:35
2	2981	(257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 16 25
3	2164	((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat$3))) and (die chip wafer)	USPAT; US-PGPUB; EPO, JPO; IBM_TDB	2002/09/07 16 25
4	37	(((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat$3))) and (die chip wafer)) and (adhesion NEAR (layer film))	USPAT; US-PGPUB; EPO, JPO; IBM_TDB	2002/09/07 15 52
5	2	(("4561011") or ("6091603")).PN.	USPAT; US-PGPUB; EPO, JPO; IBM_TDB	2002/09/07 15 52
6	722	((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat$3))) and ((die chip wafer) NEAR surface)	USPAT; US-PGPUB; EPO, JPO; IBM_TDB	2002/09/07 16 26
7	17	(((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat$3))) and ((die chip wafer) NEAR surface)) and (solder-wet$4 (solder NEAR wet$4))	USPAT; US-PGPUB; EPO, JPO; IBM_TDB	2002/09/07 16 26
8	1		USPAT	2002/09/07 16 03
9	1		USPAT	2002/09/07 16 03
10	1		USPAT	2002/09/07 16 04
11	1		USPAT	2002/09/07 16 04
12	1		USPAT	2002/09/07 16 05
13	1		USPAT	2002/09/07 16 05
14	1		USPAT	2002/09/07 16 06
15	1		USPAT	2002/09/07 16 06
16	1		USPAT	2002/09/07 16 07
17	1		USPAT	2002/09/07 16 08
18	1		USPAT	2002/09/07 16 08
19	1		USPAT	2002/09/07 16 08
20	1		USPAT	2002/09/07 16 09
21	1		USPAT	2002/09/07 16 09
22	1		USPAT	2002/09/07 16 09
23	1		USPAT	2002/09/07 16 09
24	1		USPAT	2002/09/07 16 10
25	1		USPAT	2002/09/07 16 10
26	1		USPAT	2002/09/07 16 10
27	1		USPAT	2002/09/07 16 10
28	1		USPAT	2002/09/07 16 10
29	1		USPAT	2002/09/07 16 10
30	1		USPAT	2002/09/07 16 11
31	1		USPAT	2002/09/07 16 12
32	1		USPAT	2002/09/07 16 13
33	1		USPAT	2002/09/07 16 13
34	8	((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat$3))) and ((die chip wafer) NEAR surface)) and (solder$3 NEAR thermal$2 NEAR conduct$3)	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16 20
35	29	(257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and (solder$3 NEAR thermal$2 NEAR conduct$3)	USPAT; US-PGPUB; EPO, JPO. IBM_TDB	2002/09/07 16 24

36	4327	438/122 438/125 438/612 438/118	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:24
37	7	(438/122 438/125 438/612 438/118) and (solder$3 NEAR thermal$2 NEAR conduct$3)	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:24
38	640	(438/122 438/125 438/612 438/118) and ((heat thermal) NEAR (spreader dissipat$3))	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:25
39	7	((438/122 438/125 438/612 438/118) and (solder$3 NEAR thermal$2 NEAR conduct$3)) and (die chip wafer)	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:26
40	597	((438/122 438/125 438/612 438/118) and ((heat thermal) NEAR (spreader dissipat$3))) and (die chip wafer)	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:26
41	263	((438/122 438/125 438/612 438/118) and ((heat thermal) NEAR (spreader dissipat$3))) and ((die chip wafer) NEAR surface)	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:26
42	10	(((438/122 438/125 438/612 438/118) and ((heat thermal) NEAR (spreader dissipat$3))) and ((die chip wafer) NEAR surface)) and (solder-wet$4 (solder NEAR wet$4))	USPAT; US-PGPUB; EPO, JPO; IBM_TDB	2002/09/07 16:26